

LNJ115W8PRA

Surface Mounting Chip LED

TSS-2 Type

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

- Yellow Green

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	60	mW
Forward current	I_F	20	mA
Pulse forward current *	I_{FP}	60	mA
Reverse voltage	V_R	4	V
Operating ambient temperature	T_{opr}	-30 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +100	$^\circ\text{C}$

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.**■ Lighting Color**

- Yellow Green
- Red

- Red

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	50	mW
Forward current	I_F	20	mA
Pulse forward current *	I_{FP}	60	mA
Reverse voltage	V_R	3	V
Operating ambient temperature	T_{opr}	-30 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +100	$^\circ\text{C}$

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.**■ Electro-Optical Characteristics** $T_a = 25^\circ\text{C}$

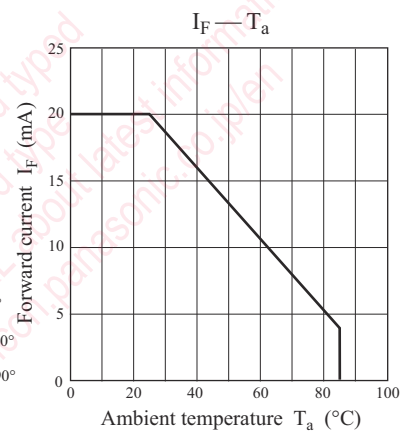
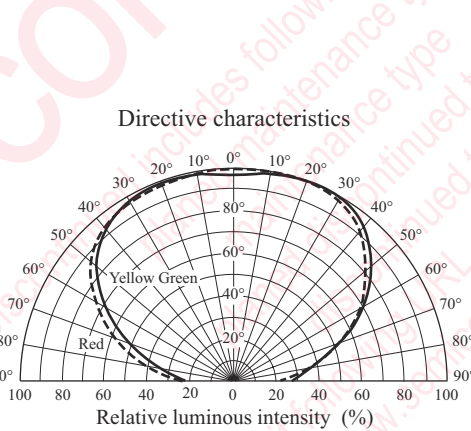
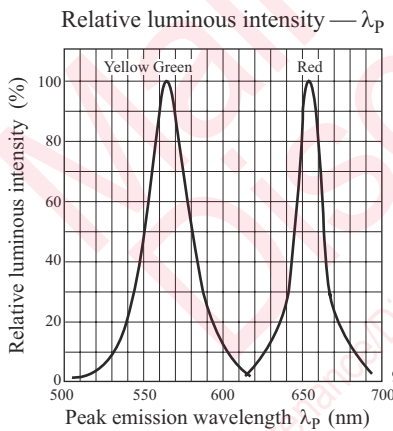
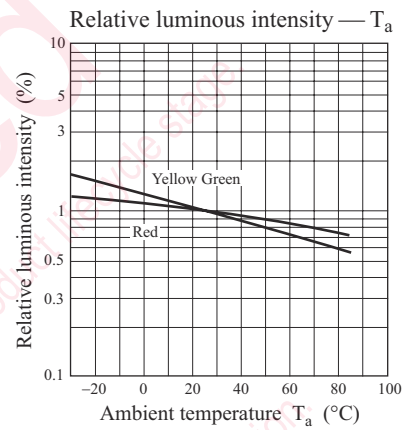
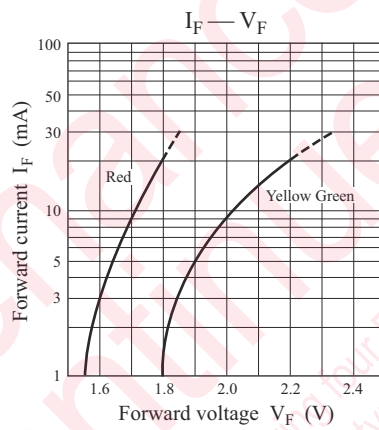
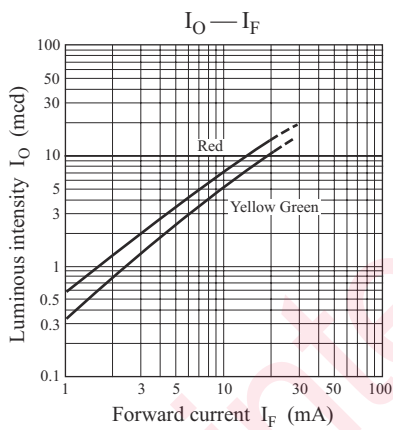
- Yellow Green

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	I_O	$I_F = 10\text{ mA}$	1.8	5.0	17.7	mcd
Reverse current	I_R	$V_R = 4\text{ V}$			10	μA
Forward voltage	V_F	$I_F = 10\text{ mA}$		2.03	2.6	V
Peak emission wavelength	λ_p	$I_F = 10\text{ mA}$		565		nm
Spectral half band width	$\Delta\lambda$	$I_F = 10\text{ mA}$		30		nm

■ Electro-Optical Characteristics (Continued) $T_a = 25^\circ\text{C}$

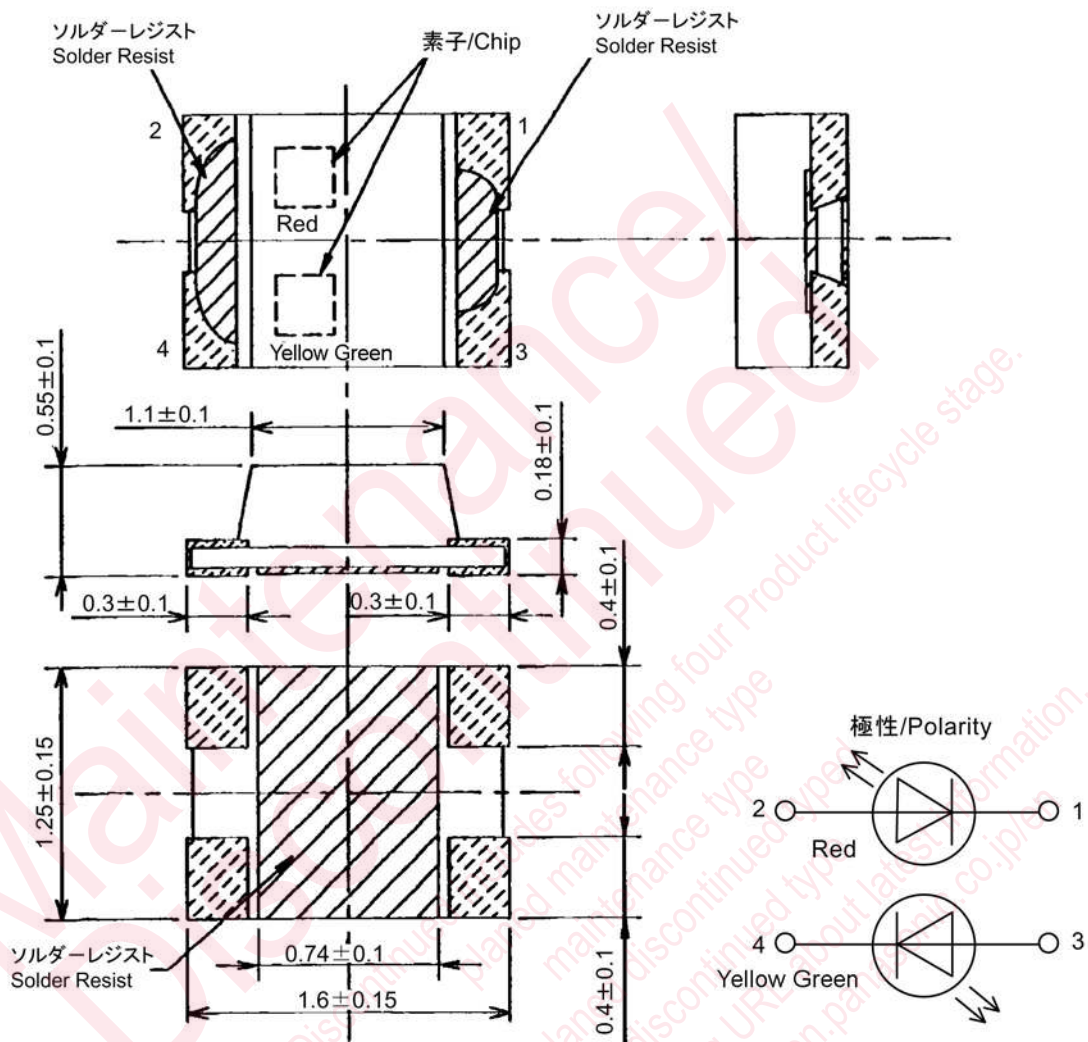
• Red

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	I_O	$I_F = 10\text{ mA}$	2.2	6.7	18.8	mcd
Reverse current	I_R	$V_R = 3\text{ V}$			100	μA
Forward voltage	V_F	$I_F = 10\text{ mA}$		1.72	2.5	V
Peak emission wavelength	λ_P	$I_F = 10\text{ mA}$		655		nm
Spectral half band width	$\Delta\lambda$	$I_F = 10\text{ mA}$		20		nm



■ Package (Unit: mm)

KLTFTN4K1540



• Pin name

- 1, 4: Cathode
- 2, 3: Anode

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